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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

RUKINO, KUNIHITO
YASUKO, YASUHIKO
YANO, KAZUO
KATO, KAZUO

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

1-23-02

2. Name and address of receiving party(ies)

Name: **HITACHI LTD**

Hitachi Device Engineering Co., Ltd.

Address: **6, Kanda Surugadai 4-chome**

Chiyoda-ku, Tokyo, Japan

☒ Other

3681, Hayano, Mobara-Shi

Chiba, Japan

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other _____

Execution Date: 4/6/00, 4/11/00, 4/12/00.

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

B. Patent Registration No.(s)

09/549,711

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Antonelli, Terry, Stout & Kraus, LLP**

Internal Address:

**1300 North Seventeenth Street
Suite 1800
Arlington, VA 22209
USA**

City: _____ State: _____ Zip: _____

6. Total number of applications and patents involved

7. Total fee (37 CFR 3.41)..... **\$40.00**

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

01-2135 (500.38472X00)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gregory E. Montone

01/23/2002

Name of Person Signing

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ASSIGNMENT

(譲 渡 証)

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the below named inventor(s), citizens of Japan by HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 3631, Hayano, Mobara-Shi, Chiba, Japan, respectively,

receipt of which is hereby acknowledged, we, the below named inventor(s), do hereby sell and assign to said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd.,

their successors and assigns, all our right, title and interest, in and for the United States of America, in and to SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd.,

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewec or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Hitachi Device Engineering co., Ltd.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) <u>Kunihito RIKINO</u>	<u>04/06/2000</u>
2) <u>Yasuhiko Saraki</u>	<u>4/12/2000</u>
3) <u>Kozuo Iwasaki</u>	<u>4/11/2000</u>
4) <u>Naoki Kato</u>	<u>4/11/2000</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____